II. Listing of Claims

1. (Cancelled).

2. (Cancelled).

3. (Cancelled).

4. (Cancelled).

5. (Cancelled).

6. (Cancelled).

7. (Cancelled).

8. (Currently Amended): A method for forming a connection within a multi-layer circuit board including a first pre-circuit assembly having a ~~first~~ conductive ground layer, and a second pre-circuit assembly including a ~~second~~ conductive layer said method comprising the steps of:

forming an aperture within said first pre-circuit assembly;

aligning said second pre-circuit assembly with said first pre-circuit assembly such that a first portion of the conductive layer of said second ~~conductive layer~~ pre-circuit assembly resides above said aperture;

attaching said first pre-circuit assembly having said aperture formed therein to said second pre-circuit assembly; and

thereafter inserting conductive material into said aperture effective to connect said first portion of the conductive layer of said second ~~conductive layer~~ pre-circuit assembly to said ~~first~~ conductive ground layer.

9. (Currently Amended): The method of claim 8 further comprising the steps of:

selectively removing ~~portions~~ areas of said second pre-circuit assembly which are disposed above said first portion of the conductive layer of said second pre-circuit assembly, thereby exposing said first portion of said conductive layer ~~second pre-circuit assembly~~; and

deforming said first portion of said conductive layer ~~second pre-circuit assembly~~, effective to cause said first portion of said second pre-circuit assembly to extend within said aperture.

10. (Original): The method of claim 9 wherein said first portion of said second pre-circuit assembly is deformed by use of a punching process.

11. (Original): The method of claim 9 wherein said first portion of said second pre-circuit assembly comprises a bridge portion.

12. (Original): The method of claim 9 wherein said first portion of said second pre-circuit assembly comprises a tab portion.

13. (Currently Amended): The method of claim 9 wherein said ~~portions~~ areas of said second pre-circuit assembly are selectively removed by use of an etching process.

14. (Original): A method for forming a connection within a multi-layer circuit board, said multi-layer circuit board including a first pre-circuit assembly including a conductive core member, a dielectric member which is attached to a top surface of said conductive core member, an adhesive layer which is coupled to a top surface of said dielectric member, and a second pre-circuit assembly including a second core member and a first and second conductive member which are respectively attached to a top and bottom surface of said second core member, said method comprising the steps of:

selectively forming at least one hole through said first pre-circuit assembly in a location where a connection to said conductive core member is desired to be formed;

registering said second pre-circuit assembly with respect to said first pre-circuit, effective to cause a portion of said second conductive member to reside above said at least one hole;

attaching said second pre-circuit assembly to said adhesive layer; and

selectively inserting a conductive material within said at least one hole, effective to connect said portion of said second conductive member to said conductive core member.

15. (Original): The method of claim 14 further comprising the step of:

selectively etching at least a portion of said second core member.

16. (Original): The method of claim 14 wherein said conductive material comprises solder.

17. (Currently Amended): The method of claim [[14]] 16 wherein said solder is selectively inserted into said at least one hole by use of a compression printing technique.

18. (Original): The method of claim 14 wherein said conductive core member is manufactured from a copper material.

19. (Original): The method of claim 17 wherein said first and said second conductive member each comprises a copper member.

20. (Original): The method of claim 19 wherein said second core member comprises an aluminum member.